

INTEGRATED CIRCUIT CHIP PACKAGE

Abstract of the Disclosure

5 A package for an integrated circuit chip adapted to operate at microwave frequencies. The package includes an electrically conductive lead frame having electrical leads extending outwardly from an inner region. A base section is adhesively affixed to a bottom portion of the lead frame. The base section and a plastic cover are configured to provide a cavity when the cover and the base section are affixed with the integrated circuit chip being disposed with such provided cavity. With another integrated circuit chip 10 package, an electrically conductive lead frame has electrical leads adapted for electrical connection to the integrated circuit chip. The base section includes a conductive member and a dielectric member. The dielectric member has an aperture disposed in registration with an inner region of the lead frame. The conductive member is electrically to a bottom surface portion of the integrated circuit. The integrated circuit chip being disposed in registration with the aperture. A plastic cover and the base section are configured to provide a cavity when the 15 cover and the bottom are affixed with the integrated circuit chip being disposed with such provided cavity and with a bottom surface portion of the conductive member being exposed exteriorly of the package.

184109.B11